CLEAF



FACED PANEL

CEPPO
LS65

SUPPORT: Chipboard, MDF FORMAT: 5600 x 2070 mm THICKNESS: from 8 to 38 mm TEXTURE ORIENTATION: Vertical BACK TEXTURE: Ceppo NOMINAL OVERTHICKNESS: +0.1 mm

LAMINATE



TYPE: HPL FORMAT: 2760 x 2040 mm THICKNESS: 0.9 mm EDGE

CEPPO LS65

TYPE: ABS HEIGHT: from 15 to 350 mm THICKNESS: from 0.5 to 2.0 mm